

REV	MODIFICATION
A	ECXXXXX

Specification

1.MATERIAL:

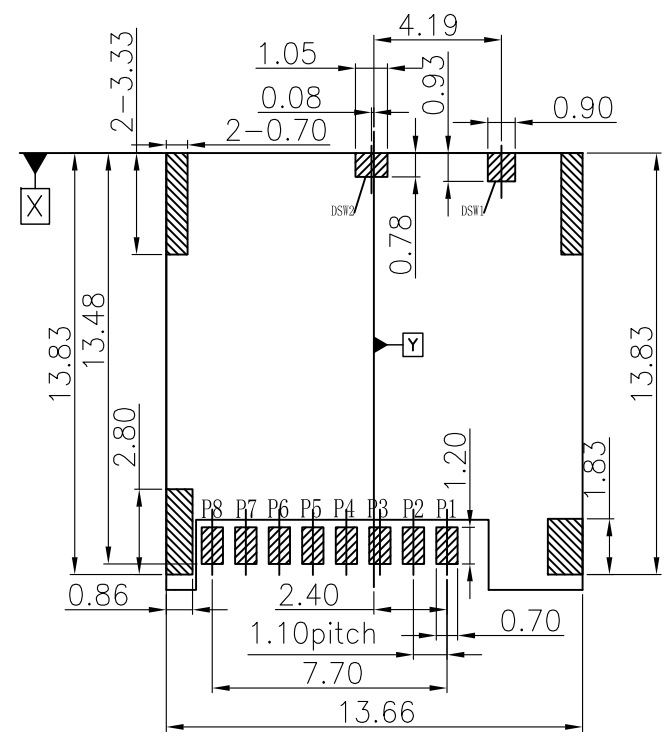
- 1.1 Insulator:High Temperature Thermoplastic,
LCP black UL94V-0.
- 1.2 Terminal: Phosphor Bronze.
- 1.3 Shell: STAINLESS STEEL.

2.Plating:

- 2.1 Terminal: Plated 80u"min Ni Overall
Plated 1u"min Au Selective contact area
Plated 1u"min AU over Ni on solder area
- 2.2 Shell: Plated 1u"min AU overll 50u"min Ni

3.Property:

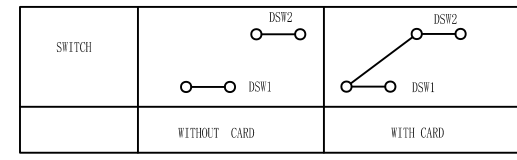
- 3.1 Current Rating :0.5A AC/DC max.
- 3.2 Voltage Rating :12V AC/DC
- 3.3 Ambient Temperature Range :-20°C~+60°C
- 3.4 Ambient Humidity Range :95% R.H. Max.
- 3.5 Contact Resistance:100mΩ max.
- 3.6 Insulation Resistance:1000MΩ min./500VDC
- 3.7 Durability:5000 cycles



RECOMMEND P.C.B LAYOUT
(General tolerance ± 0.05)

- PAD AREA
- KEEP OUT AREA
- GND PATTERN ONLY

PIN NO.	PIN ASSIGNMENT
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X $\pm$ 0.50	X* $\pm$ 5 °		
.X $\pm$ 0.30	.X* $\pm$ 2 °		
.XX $\pm$ 0.20	.XX* $\pm$ 1 °	名 稱(TITLE) MICRO SD 1.28H PUSH SMT	
單 位(UNIT) mm	料 號(PART NO.) 7MSDP-FA-0024	圖 號(DWG NO.) 7MSDP-FA-0024	
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	尺 寸 SCALE 1:1 圖 例 PROJ.
			張 數 SHEET 2/2 更 改 REV A